ABSOLUTE MAXIMUM RATINGS (T_A=25ºC, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation at 8/20µs waveform	P_{PP}	150	W
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	+/- 30 +/- 30	kV
Lead soldering temperature	T_L	260 (10 sec.)	
Operating junction temperature range	T_J	-55 to +150	
Storage temperature range	T_{STG}	-55 to +150	

ELECTRICAL CHARACTERISTICS (T_A=25)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V_{RWM}				5.0	V
Reverse breakdown voltage	V_{BR}	I_T=1mA Pin2 to 1	6.0	7.5	9.0	V
Reverse leakage current	I_R	V_{RWM}=5V		0.01	0.1	µA
Forward voltage	V_F	I_F=15mA		0.8	1.1	V

FIG.3: Pulse derating curve

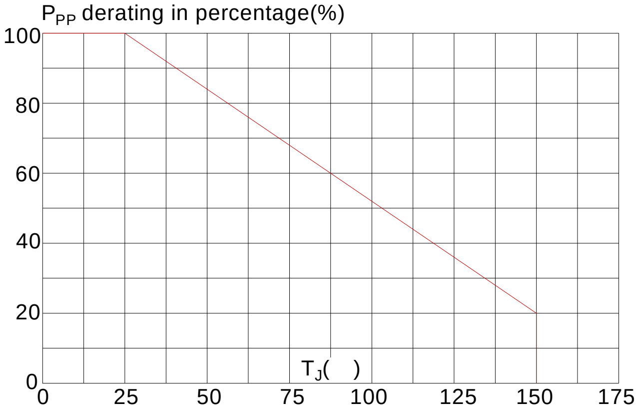
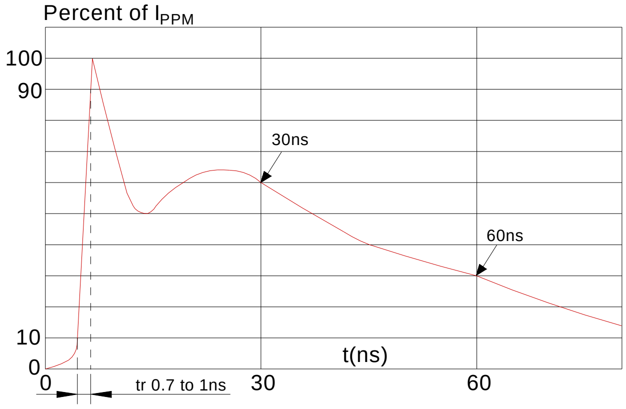
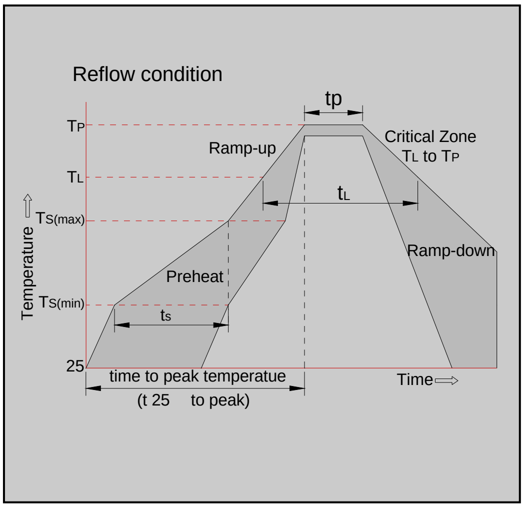


FIG.4: ESD clamping (30kV contact)

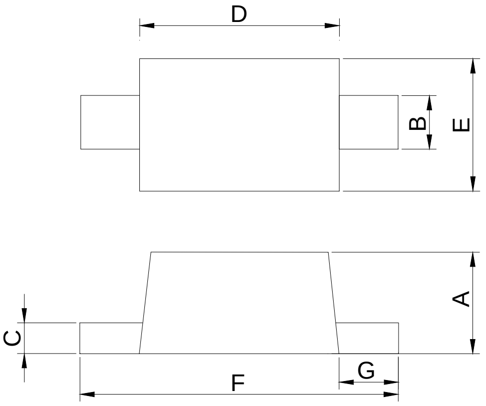


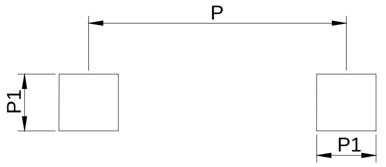
SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150
	-Temperature Max($T_{s(max)}$)	+200
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L)to peak)		3 /sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 /sec. Max
Reflow	-Temperature(T_L)(Liquidus)	+217
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)
Time within 5 of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6 /sec. Max
Time 25 to Peak Temp (T_P)		8 min. Max
Do not exceed		+260



PACKAGE MECHANICAL DATA

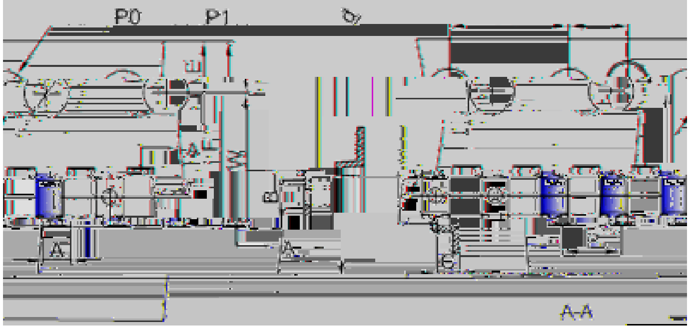


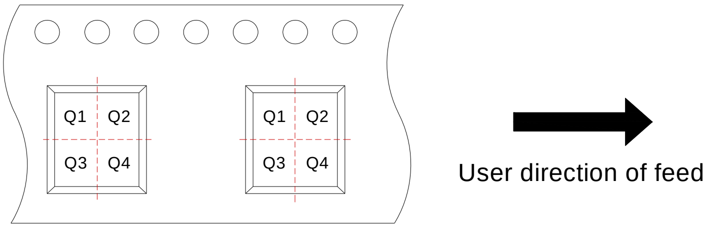


Land Pattern

Symbol	Millimeters			Inches		
	Min	**Typ**	**Max**	**Min**	**Typ**	**Max**
A	0.50	0.61	0.77	0.020	0.024	0.030
B	0.25	0.30	0.40	0.010	0.012	0.016
C	0.07	0.13	0.20	0.003	0.005	0.008
D	1.10	1.20	1.30	0.043	0.047	0.051
E	0.70	0.80	0.90	0.028	0.031	0.035
F	1.50	1.60	1.70	0.059	0.063	0.067
G	0.15	0.20	0.25	0.006	0.008	0.010
P1	0.60			0.024		
P	1.42			0.056		

TAPE AND REEL SPECIFICATION-SOD-523

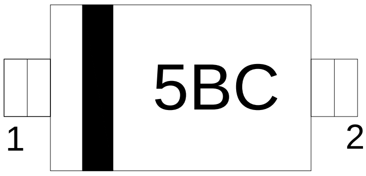




Pin 1 quadrant:Q1&Q2

ORDERING INFORMATION

MARKING CODE

Part Number	Marking Code
JEU05D5-AU	

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